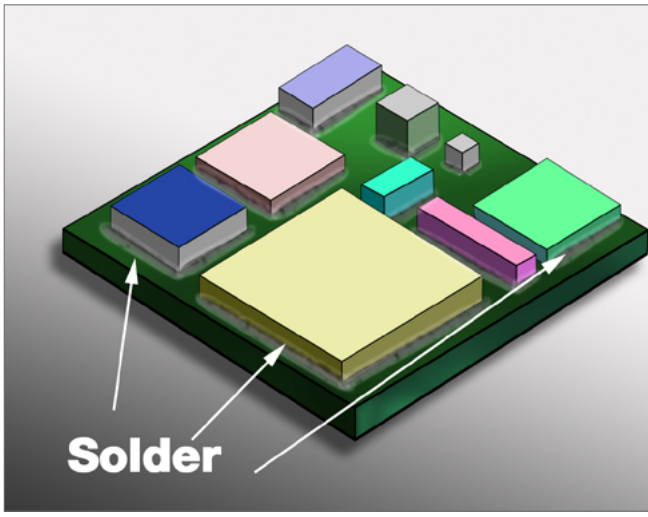
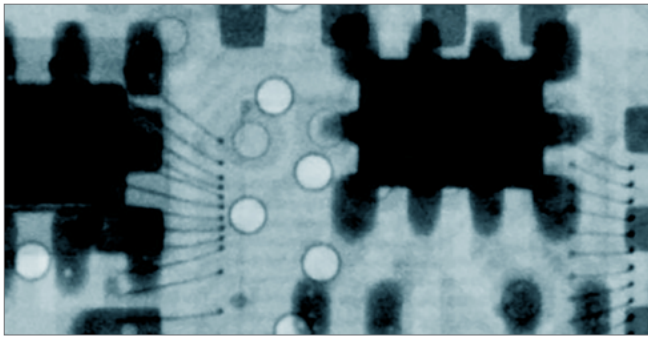
ALPHA® Solder Paste

NCP & WS Solder Pastes for Fine Pitch Semiconductor Package and Modules

DESIGNED FOR T5, T6 AND T7 SAC305 PROCESSING, FOR PITCH < 80µM. (008004 COMPATIBLE)

- Excellent print consistency with high throughput capability across multiple package designs
- Halide and Halogen free formulation
- Excellent wetting and solderability with minimum voiding on various finishes (Cu, CuOSP, NiAu)
- Low temperature, easy to remove Water Soluble flux residues in standard DI washing (< 40°C)
- High Reliability No Clean flux residues able to pass IPC SIR and Electromigration requirements





SOLDER PASTE PRODUCT LINE

Product Name	Material Type	Deposition Method			Properties					Powder Size				Component Type
		Dispense	Print	Dip	Halide Free	Activty	Tackiness	Fine Pitch Capable	Lead Free	Type 3	Type 4	Type 5	Type 6	
NCP1213	No Clean	o			o	Hi	Hi			o				Leadframe
NCP-390			o		o	Hi	Hi	o	o		o	o	o	SiP/BGA
NCP-340			o		o	Hi	Hi	o	o		o			SiP/BGA
NCP-LR002			o		o	Hi	Hi	o	o		o			SiP/BGA
WS609	Water Soluble		o		o	Hi	Hi		o	o	o			SiP/BGA
WS693CPS			o		o	Hi	Hi	o	o		o	o	o	SiP/BGA
WS698CPS			o		o	Hi	Hi	o	o				o	SiP/BGA
WS699CPS			o		o	Hi	Hi	o	o				o	SiP/BGA

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